

# Switch-mode Power Rectifier

# **DPAK Surface Mount Package**

# MBRD835L, SBRD8835L

This switch-mode power rectifier which uses the Schottky Barrier principle with a proprietary barrier metal, is designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

#### **Features**

- Low Forward Voltage
- 150 °C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- · Compact Size
- · Lead Formed for Surface Mount
- SBRD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### **Mechanical Characteristics**

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260 °C Max. for 10 Seconds
- Shipped 75 Units Per Plastic Tube
- ESD Rating:
  - ◆ Machine Model = C (> 400 V)
  - ♦ Human Body Model = 3B (> 8000 V)

# SCHOTTKY BARRIER RECTIFIER 8.0 AMPERES, 35 VOLTS





### **MARKING DIAGRAM**



B835LG = Specific Device Number A = Assembly Location\*

Y = Year WW = Work Week G = Pb-Free Device

\* The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

### ORDERING INFORMATION

| Device            | Package           | Shipping <sup>†</sup> |
|-------------------|-------------------|-----------------------|
| MBRD835LT4G       | DPAK              | 2500 /                |
|                   | (Pb-Free)         | Tape & Reel           |
| SBRD8835LT4G-VF01 | DPAK<br>(Pb-Free) | 2500 /<br>Tape & Reel |

### **DISCONTINUED** (Note 1)

1

| MBRD835LG        | DPAK      | 75 Units / Rail |
|------------------|-----------|-----------------|
|                  | (Pb-Free) |                 |
| SBRD8835LG       | DPAK      | 75 Units / Rail |
|                  | (Pb-Free) |                 |
| SBRD8835LG-VF01  | DPAK      | 75 Units / Rail |
|                  | (Pb-Free) |                 |
| SBRD835LT4G-VF01 | DPAK      | 2,500 /         |
|                  | (Pb-Free) | Tape & Reel     |
| SBRD8835LT4G     | DPAK      | 2,500 /         |
|                  | (Pb-Free) | Tape & Reel     |

- † For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, <a href="mailto:BRD8011/D">BRD8011/D</a>.
- DISCONTINUED: This device is not available. Please contact your onsemi representative for information. The most current information on this device may be available on <a href="https://www.onsemi.com">www.onsemi.com</a>.

### **MAXIMUM RATINGS**

| Rating  | Symbol   | Value       | Unit |
|---|--|-------------|------|
| Peak Repetitive Reverse Voltage<br>Working Peak Reverse Voltage<br>DC Blocking Voltage                            | V <sub>RRM</sub><br>V <sub>RWM</sub><br>V <sub>R</sub> | 35          | V    |
| Average Rectified Forward Current (T <sub>C</sub> = 88 °C)  | I <sub>F(AV)</sub>                                     | 8.0         | Α    |
| Peak Repetitive Forward Current (Square Wave, Duty = 0.5, T <sub>C</sub> = 80 °C)                                 | I <sub>FRM</sub>                                       | 16          | А    |
| Non-Repetitive Peak Surge Current<br>(Surge applied at rated load conditions, halfwave, single phase, 60 Hz)      | I <sub>FSM</sub>                                       | 75          | Α    |
| Repetitive Avalanche Current (Current Decaying Linearly to Zero in 1 μs, Frequency Limited by T <sub>Jmax</sub> ) | I <sub>AR</sub>  | 2.0         | Α    |
| Storage / Operating Case Temperature  | T <sub>stg</sub>                                       | -65 to +150 | °C   |
| Operating Junction Temperature (Note 1)   | TJ   | -65 to +150 | °C   |
| Voltage Rate of Change (Rated V <sub>R</sub> )  | dv/dt  | 10,000      | V/μs |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

### THERMAL CHARACTERISTICS

| Characteristic                                  | Symbol          | Value | Unit |
|---|-----------------|-------|------|
| Thermal Resistance-Junction-to-Case             | $R_{	heta JC}$  | 2.8   | °C/W |
| Thermal Resistance-Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 80    | °C/W |

<sup>2.</sup> Rating applies when surface mounted on the minimum pad size recommended.

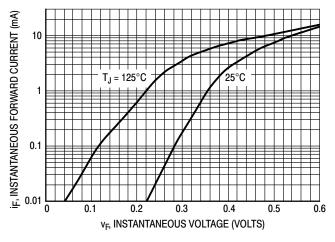
### **ELECTRICAL CHARACTERISTICS**

| Characteristic  | Symbol         | Value        | Unit |
|---|----------------|--------------|------|
| Maximum Instantaneous Forward Voltage (Note 3) ( $i_F$ = 8 Amps, $T_C$ = +25 °C) ( $i_F$ = 8 Amps, $T_C$ = +125 °C)   | V <sub>F</sub> | 0.51<br>0.41 | V    |
| Maximum Instantaneous Reverse Current (Note 3) (Rated dc Voltage, $T_C = +25$ °C) (Rated dc Voltage, $T_C = +100$ °C) | I <sub>R</sub> | 1.4<br>35    | mA   |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 3. Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2%.

<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction-to-Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

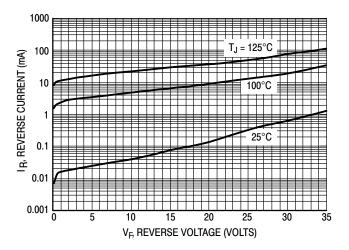
## **TYPICAL CHARACTERISTICS**



0.01 0.1 0.2 0.3 0.4 0.5 0.6 V<sub>F</sub>, INSTANTANEOUS VOLTAGE (VOLTS)

Figure 1. Maximum Forward Voltage

Figure 2. Typical Forward Voltage



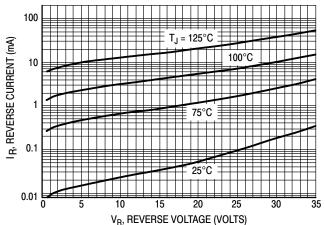


Figure 3. Maximum Reverse Current

Figure 4. Typical Reverse Current

### TYPICAL CHARACTERISTICS

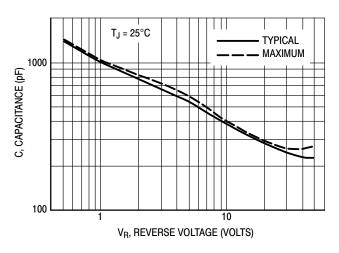


Figure 5. Maximum and Typical Capacitance

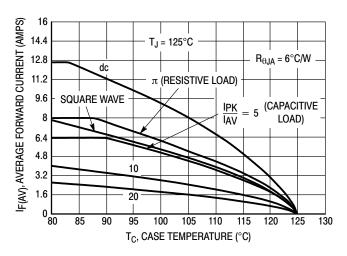


Figure 6. Current Derating, Infinite Heatsink

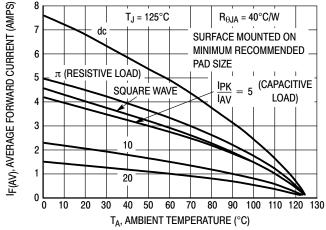


Figure 7. Current Derating

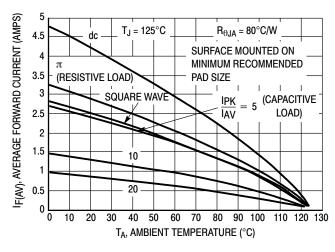


Figure 8. Current Derating, Free Air

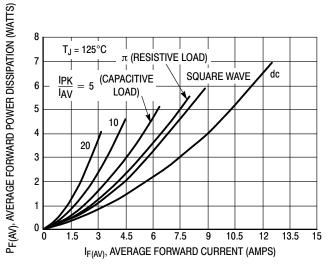


Figure 9. Forward Power Dissipation

## **REVISION HISTORY**

| Revision | Description of Changes   | Date     |
|----------|--|----------|
| 14       | MBRD835LG, SBRD8835LG, SBRD8835LG-VF01, SBRD835LT4G-VF01, SBRD8835LT4G OPN Marked as Discontinued + Rebranded the Data Sheet to <b>onsemi</b> format | 7/4/2025 |

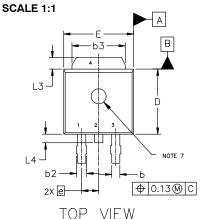
This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.

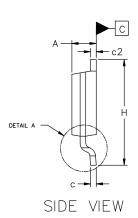




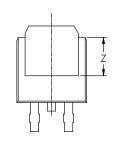
### DPAK3 6.10x6.54x2.28, 2.29P CASE 369C **ISSUE J**

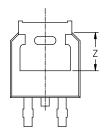
**DATE 12 AUG 2025** 

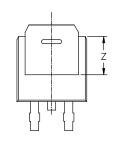


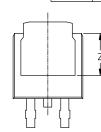


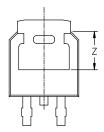
| MILLIMETERS |          |          |       |  |
|-------------|----------|----------|-------|--|
| DIM         | MIN      | NOM      | MAX   |  |
| А           | 2.18     | 2.28     | 2.38  |  |
| A1          | 0.00     |          | 0.13  |  |
| b           | 0.63     | 0.76     | 0.89  |  |
| b2          | 0.72     | 0.93     | 1.14  |  |
| b3          | 4.57     | 5.02     | 5.46  |  |
| С           | 0.46     | 0.54     | 0.61  |  |
| c2          | 0.46     | 0.54     | 0.61  |  |
| D           | 5.97     | 6.10     | 6.22  |  |
| E           | 6.35     | 6.54     | 6.73  |  |
| е           | :        | 2.29 BSC |       |  |
| Н           | 9.40     | 9.91     | 10.41 |  |
| L           | 1.40     | 1.59     | 1.78  |  |
| L1          | 2.90 REF |          |       |  |
| L2          | 0.51 BSC |          |       |  |
| L3          | 0.89     |          | 1.27  |  |
| L4          |          |          | 1.01  |  |
| Z           | 3.93     |          |       |  |











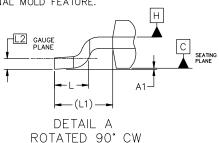
BOTTOM VIEW

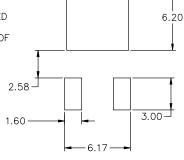
ALTERNATE CONSTRUCTIONS

### NOTES:

- DIMENSIONING AND TOLERANCING ASME Y14.5M, 2018.

- CONTROLLING DIMENSION: MILLIMETERS.
  THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS b3, L3, AND Z.
  DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR
  BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15mm PER SIDE.
- DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- DATUMS A AND B ARE DETERMINED AT DATUM PLANE H. OPTIONAL MOLD FEATURE.





-5.80

RECOMMENDED MOUNTING FOOTPRINT\*

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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| DESCRIPTION:     | DPAK3 6.10x6.54x2.28, 2.2 | 9P   | PAGE 1 OF 2 |

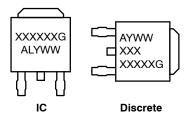
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## DPAK3 6.10x6.54x2.28, 2.29P

CASE 369C ISSUE J

**DATE 12 AUG 2025** 

# GENERIC MARKING DIAGRAM\*



XXXXXX = Device Code

A = Assembly Location

L = Wafer Lot

Y = Year

WW = Work Week

G = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

| STYLE 1:<br>PIN 1. BASE<br>2. COLLECTOR<br>3. EMITTER<br>4. COLLECTOR | STYLE 2:<br>PIN 1. GATE<br>2. DRAIN<br>3. SOURCE<br>4. DRAIN | STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE | STYLE 4: PIN 1. CATHODE 2. ANODE 3. GATE 4. ANODE | STYLE 5:<br>PIN 1. GATE<br>2. ANODE<br>3. CATHODE<br>4. ANODE |
|---|--|--|---|---|
|---|--|--|---|---|

| STYLE 6:               | STYLE 7:                    | STYLE 8:                  | STYLE 9:                          | STYLE 10:                 |
|------------------------|-----------------------------|---------------------------|-----------------------------------|---------------------------|
| PIN 1. MT1             | PIN 1. GATE                 | PIN 1. N/C                | PIN 1. ANODE                      | PIN 1. CATHODE            |
| 2. MT2                 | <ol><li>COLLECTOR</li></ol> | <ol><li>CATHODE</li></ol> | 2. CATHODE                        | 2. ANODE                  |
| <ol><li>GATE</li></ol> | <ol><li>EMITTER</li></ol>   | <ol><li>ANODE</li></ol>   | <ol><li>RESISTOR ADJUST</li></ol> | <ol><li>CATHODE</li></ol> |
| 4. MT2                 | <ol><li>COLLECTOR</li></ol> | <ol><li>CATHODE</li></ol> | 4. CATHODE                        | <ol><li>ANODE</li></ol>   |
|                        |                             |                           |                                   |                           |

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| DESCRIPTION:     | DPAK3 6.10x6.54x2.28, 2.2 | 9P  | PAGE 2 OF 2 |

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